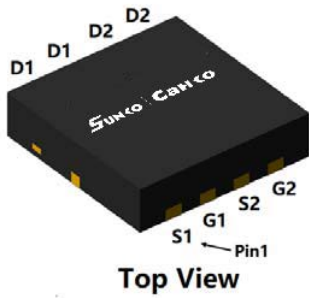
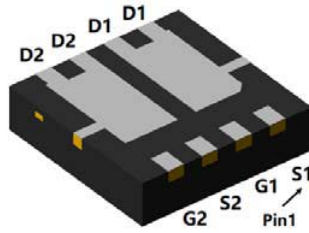
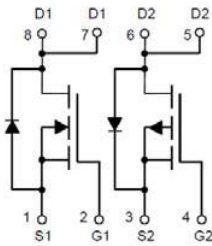


N-Channel Enhancement Mode Field Effect Transistor


Top View

Bottom View

DFN3333-8L

Product Summary

- V_{DS} 30V
- I_D 30A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) $<13m\Omega$
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) $<16m\Omega$
- 100% EAS Tested

General Description

- Trench Power LV MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Moisture Sensitivity Level 3
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- High current load applications
- Load switch
- Hard switched and high frequency circuits
- Uninterruptible power supply

■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	30	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current	$T_A=25^\circ\text{C}$	I_D	9.7	A
	$T_A=100^\circ\text{C}$		6.1	
	$T_C=25^\circ\text{C}$		30	
	$T_C=100^\circ\text{C}$		21	
Pulsed Drain Current ^A		I_{DM}	115	A
Total Power Dissipation ^B	$T_A=25^\circ\text{C}$	P_D	2	W
	$T_A=100^\circ\text{C}$		0.8	
	$T_C=25^\circ\text{C}$		21	
	$T_C=100^\circ\text{C}$		10.5	
Single Pulse Avalanche Energy		E_{AS}	140	mJ
Thermal Resistance-Junction to Ambient ^C		$R_{\theta JA}$	60	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-to-Case		$R_{\theta JC}$	7.1	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range		T_J, T_{STG}	$-55 \sim +150$	$^\circ\text{C}$

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SCQ3622A	F1	Q3622	5000	10000	100000	13" reel

■ Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions		Min	Typ	Max	Units
Static Parameter							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA		30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V	T _J =25℃			1	μA
			T _J =55℃			5	
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} =0V				±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA		1.0	1.5	2.5	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} = 10V, I _D =20A			7.5	13	mΩ
		V _{GS} = 4.5V, I _D =10A			11.5	16	
Diode Forward Voltage	V _{SD}	I _S =15A, V _{GS} =0V			0.85	1.2	V
Maximum Body-Diode Continuous Current	I _S					30	A
Dynamic Parameters							
Input Capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V, f=1MHZ			1015		pF
Output Capacitance	C _{oss}				201		
Reverse Transfer Capacitance	C _{rss}				164		
Switching Parameters							
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =20V, I _D =20A			23.6		nC
Gate-Source Charge	Q _{gs}				3.9		
Gate-Drain Charge	Q _{gd}				7.0		
Reverse Recovery Charge	Q _{rr}	I _F =15A, di/dt=100A/us			0.2		
Reverse Recovery Time	t _{rr}				5		
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DD} =20V, I _D =2A, R _{GEN} =3Ω			7		ns
Turn-on Rise Time	t _r				19		
Turn-off Delay Time	t _{D(off)}				24		
Turn-off fall Time	t _f				24		

A. Repetitive rating; pulse width limited by max. junction temperature.

B. P_d is based on max. junction temperature, using junction-case thermal resistance.

C. The value of R_{θJA} is measured with the device mounted on 1 in2 FR-4 board with 2oz. Copper, in the still air environment with T_A =25°C. The maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.

■ Typical Performance Characteristics

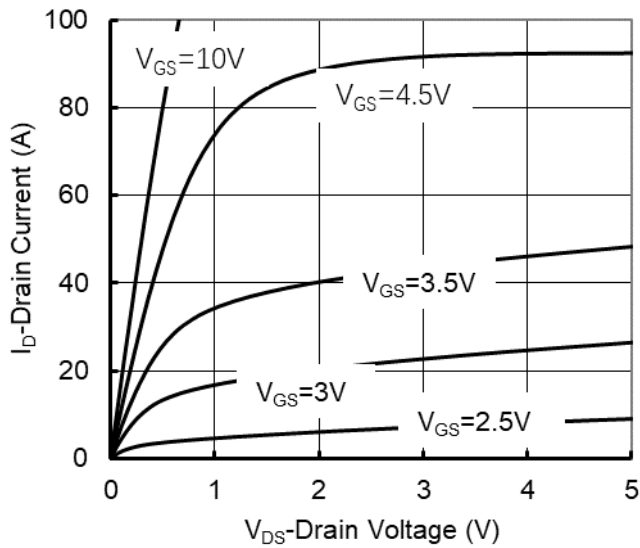


Figure1. Output Characteristics

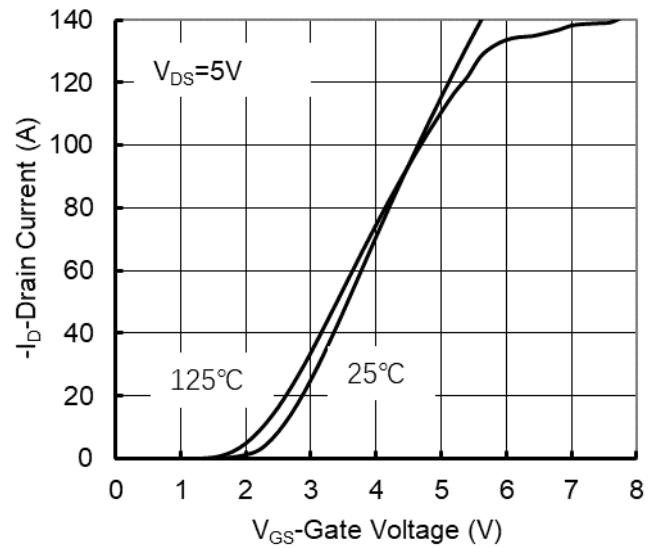


Figure2. Transfer Characteristics

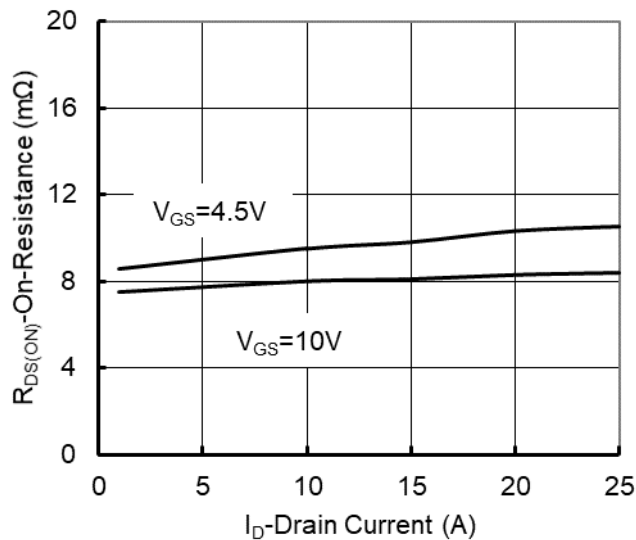


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

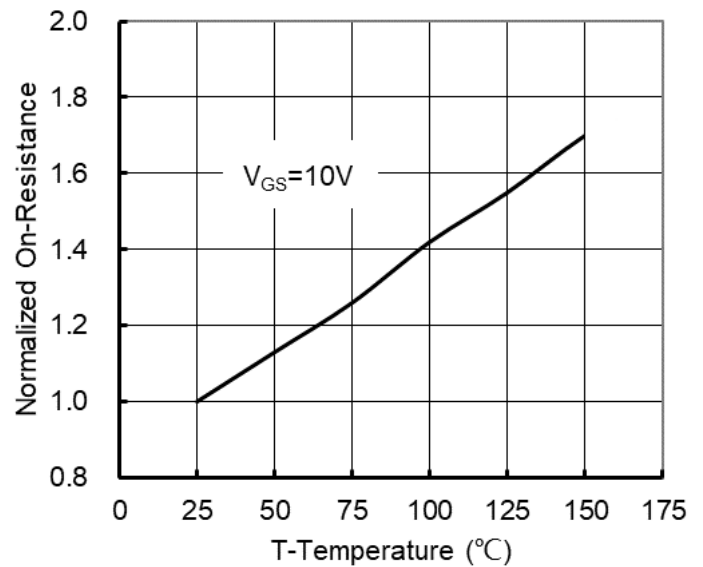


Figure 4: On-Resistance vs. Junction Temperature

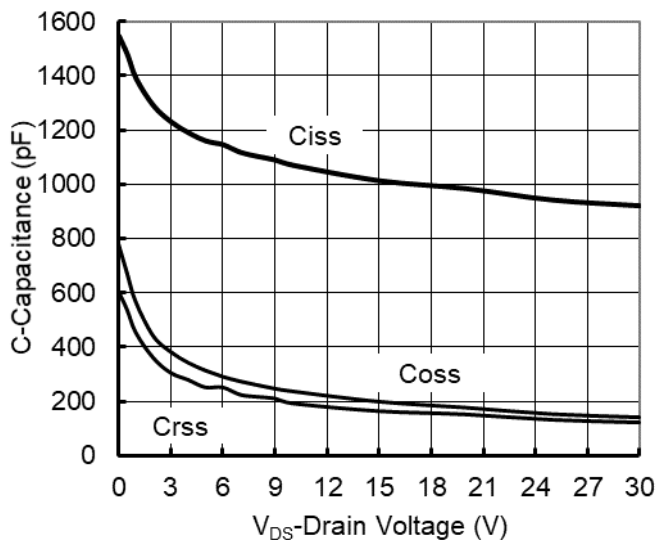


Figure5. Capacitance Characteristics

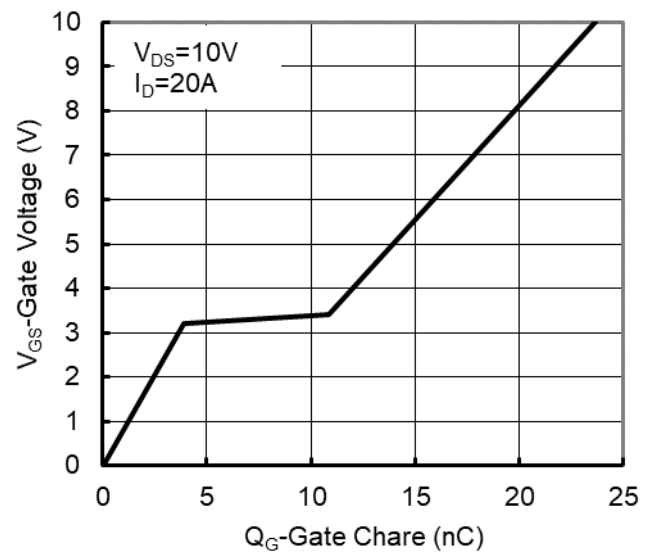


Figure6. Gate Charge

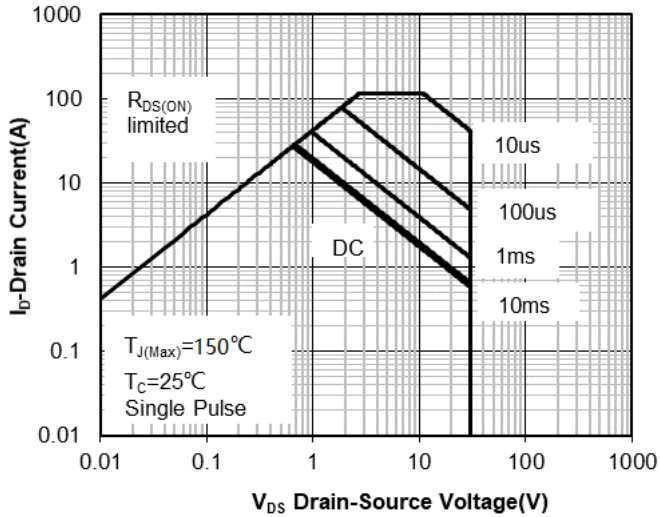


Figure7. Safe Operation Area

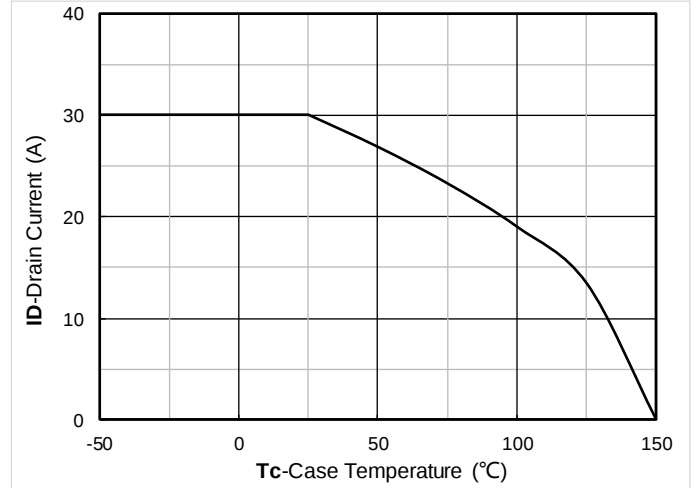


Figure8. Maximum Continuous Drain Current vs Case Temperature

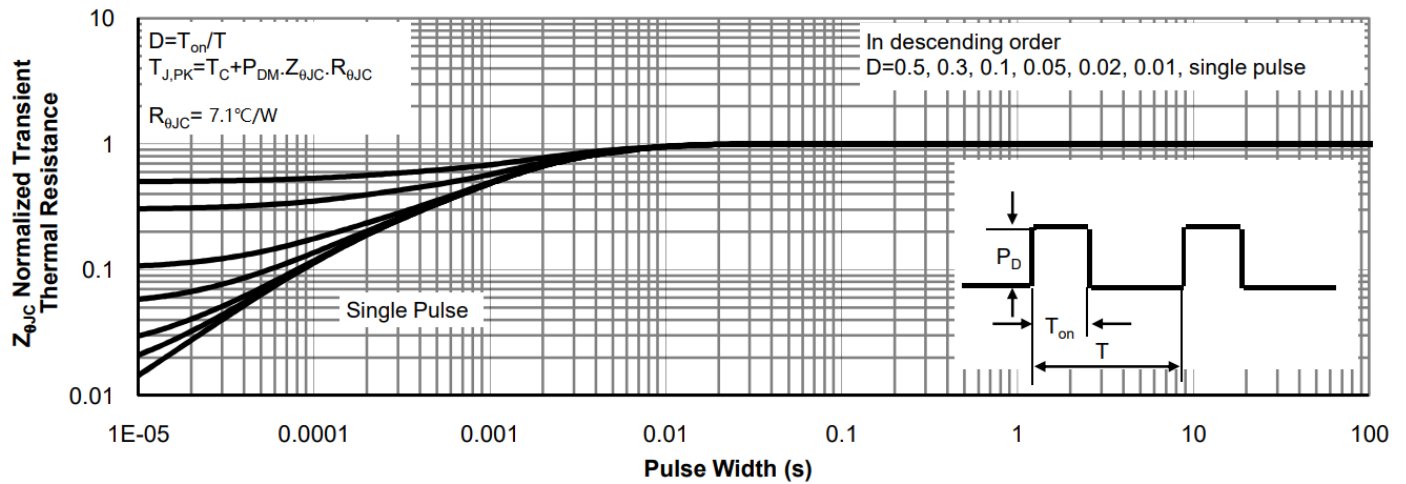
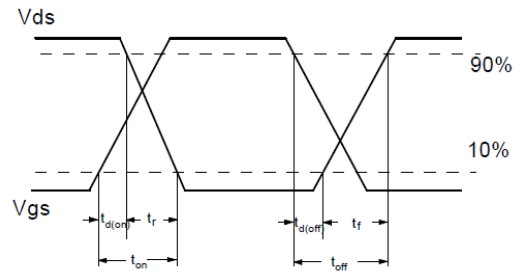
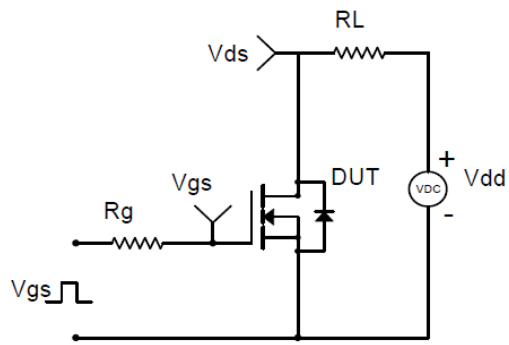
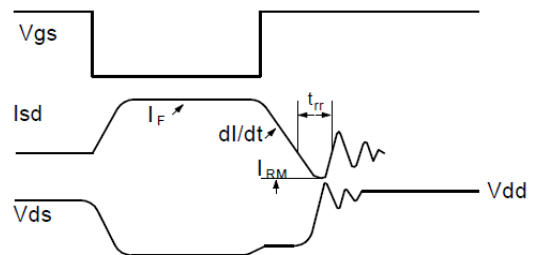
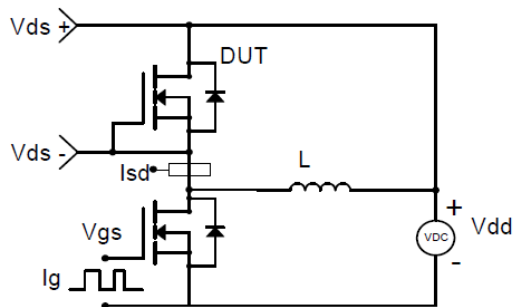


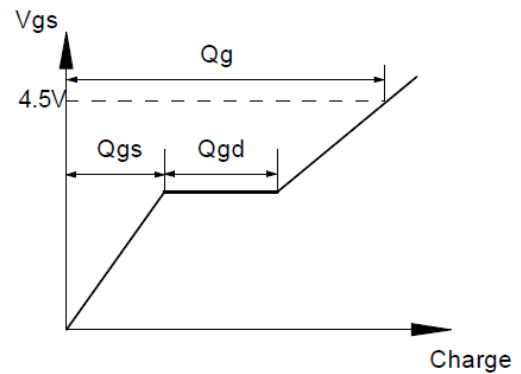
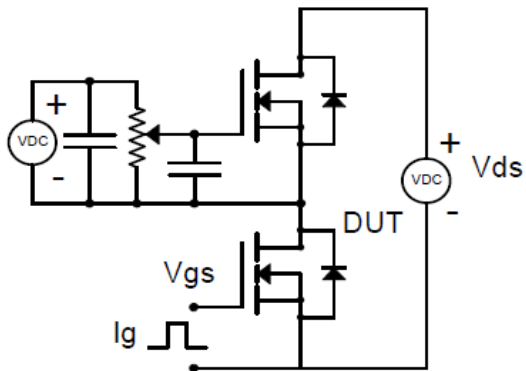
Figure9. Normalized Maximum Transient Thermal Impedance



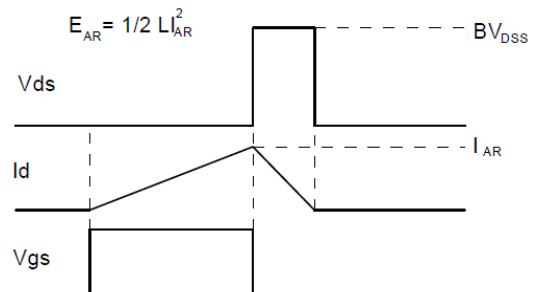
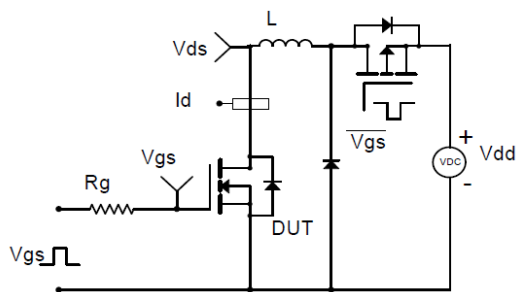
Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

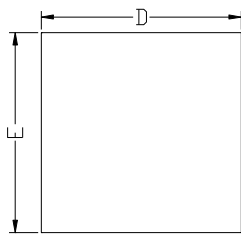


Gate Charge Test Circuit & Waveform

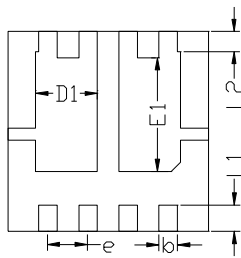


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

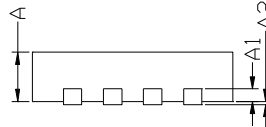
■DFN3333-8L Package information



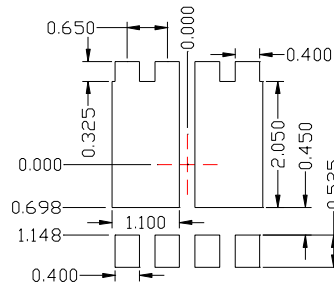
Top View
正面视图



Bottom View
背面视图



Side View
侧面视图



Suggested Solder Pad Layout
Top View

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	3.15	3.25	3.35
E	3.15	3.25	3.35
A	0.70	0.80	0.90
A1	0.20 BSC		
A2			0.10
D1	0.90	1.00	1.10
E1	1.75	1.85	1.95
L1	0.325	0.425	0.525
L2	0.325 BSC		
b	0.20	0.30	0.40
e	0.65 BSC		

Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.10 mm.
3. The pad layout is for reference purposes only.

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